

N-Channel MOSFET



Lead Free Package and Finish

Applications:

- Adaptor
- Charger
- SMPS

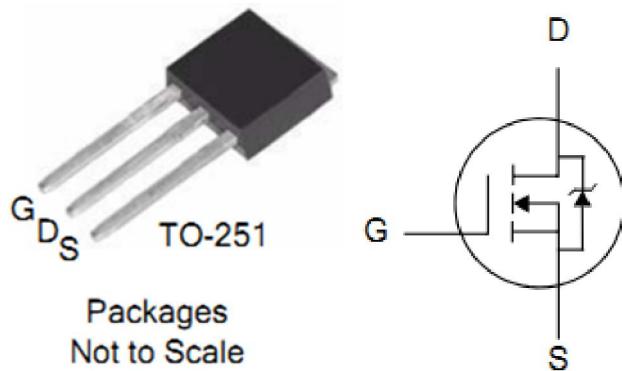
V_{DSS}	$R_{DS(ON)}(\text{Typ.})$	I_D
60V	33mΩ	21A

Features:

- RoHS Compliant
- Low ON Resistance
- Low Gate Charge
- Peak Current vs Pulse Width Curve
- Inductive Switching Curves

Ordering Information

PART NUMBER	PACKAGE	BRAND
FTU45N06N	TO-251	IPS

Absolute Maximum Ratings $T_J=25^\circ\text{C}$ unless otherwise specified

Symbol	Parameter	Rating	Units
V_{DSS}	Drain-to-Source Voltage	60	V
I_D	Continuous Drain Current $T_c=25^\circ\text{C}$	21	A
	Continuous Drain Current $T_c=100^\circ\text{C}$	13.7	A
I_{DM}^{a1}	Pulsed Drain Current	84	A
E_{AS}^{a2}	Avalanche Energy	42.25	mJ
P_D	Power Dissipation $T_c=25^\circ\text{C}$	31	W
	Derating Factor above 25°C	0.248	W/ $^\circ\text{C}$
V_{GS}	Gate-to-Source Voltage	± 20	V
T_J and T_{STG}	Operating Junction and Storage Temperature Range	150, -55 to 150	$^\circ\text{C}$
T_L	Maximum Temperature for Soldering	300	$^\circ\text{C}$

Thermal Resistance

Symbol	Parameter	Max.	Units	Test Conditions
$R_{\theta JC}$	Junction-to-Case	4	$^\circ\text{C}/\text{W}$	Water cooled heatsink, P_D adjusted for a peak junction temperature of $+150^\circ\text{C}$.
$R_{\theta JA}$	Junction-to-Ambient	100		1 cubic foot chamber, free air.

OFF Characteristics $T_C=25^\circ\text{C}$ unless otherwise specified

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
BV_{DSS}	Drain-to-Source Breakdown Voltage	60	--	--	V	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_D=250\mu\text{A}$
I_{DSS}	Drain-to-Source Leakage Current	--	--	1	μA	$\text{V}_{\text{DS}}=60\text{V}, \text{V}_{\text{GS}}=0\text{V}$ $\text{T}_J=25^\circ\text{C}$
		--	--	100		$\text{V}_{\text{DS}}=48\text{V}, \text{V}_{\text{GS}}=0\text{V}$ $\text{T}_J=125^\circ\text{C}$
I_{GSS}	Gate-to-Source Forward Leakage	--	--	+100	nA	$\text{V}_{\text{GS}}=+20\text{V}$
	Gate-to-Source Reverse Leakage	--	--	-100		$\text{V}_{\text{GS}}= -20\text{V}$

ON Characteristics $T_J=25^\circ\text{C}$ unless otherwise specified

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
$\text{R}_{\text{DS(ON)}}$	Static Drain-to-Source On-Resistance	--	33	45	$\text{m}\Omega$	$\text{V}_{\text{GS}}=10\text{V}, \text{I}_D=5\text{A}$
		--	49	66	$\text{m}\Omega$	$\text{V}_{\text{GS}}=4.5\text{V}, \text{I}_D=3\text{A}$
$\text{V}_{\text{GS(TH)}}$	Gate Threshold Voltage	1.8	--	2.8	V	$\text{V}_{\text{DS}}=\text{V}_{\text{GS}}, \text{I}_D=250\mu\text{A}$
Pulse width $\leqslant 300\mu\text{s}$; duty cycle $\leqslant 2\%$						

Dynamic Characteristics Essentially independent of operating temperature

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
R_g	Gate Resistance	--	3	--	Ω	$f=1\text{MHz}$,
C_{iss}	Input Capacitance	--	504	--	pF	$\text{V}_{\text{GS}}= 0\text{V}, \text{V}_{\text{DS}} = 30\text{V}$ $f = 1.0\text{MHz}$
C_{oss}	Output Capacitance	--	56.9	--		
C_{rss}	Reverse Transfer Capacitance	--	32.7	--		
$Q_g(\text{V}_{\text{GS}}=4.5\text{V})$	Total Gate Charge	--	5.6	--	nC	$\text{I}_D=10\text{A}, \text{V}_{\text{DD}}=30\text{V}$ $\text{V}_{\text{GS}} = 4.5\text{V}/10\text{V}$
$Q_g(\text{V}_{\text{GS}}=10\text{V})$	Total Gate Charge		11.2			
Q_{gs}	Gate-to-Source Charge	--	2	--		
Q_{gd}	Gate-to-Drain ("Miller") Charge	--	3.3	--		

Resistive Switching Characteristics Essentially independent of operating temperature

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
$t_d(\text{ON})$	Turn-on Delay Time	--	8	--	ns	$\text{V}_{\text{DD}}=30\text{V}, \text{I}_D=10\text{A},$ $\text{V}_{\text{GS}}=10\text{V} \text{ R}_g=3\Omega$
t_{rise}	Rise Time	--	3.6	--		
$t_d(\text{OFF})$	Turn-Off Delay Time	--	19.2	--		
t_{fall}	Fall Time	--	3.2	--		

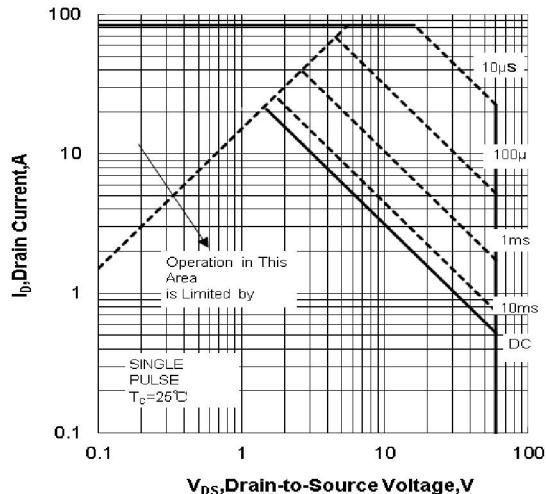
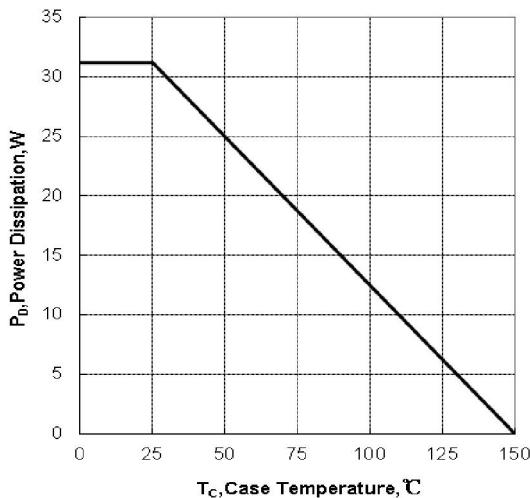
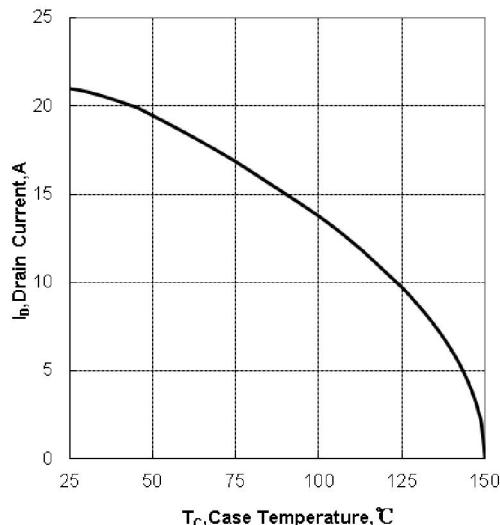
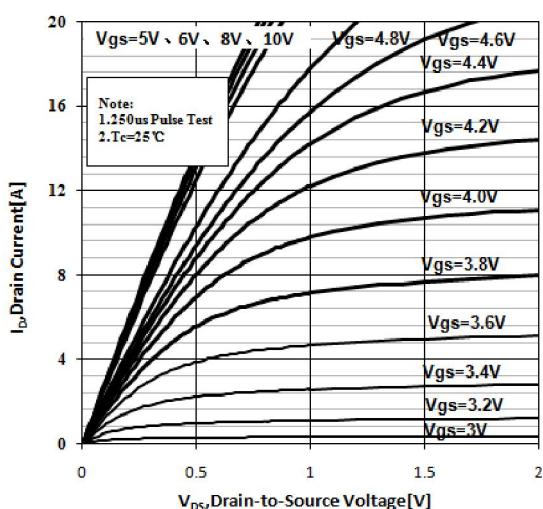
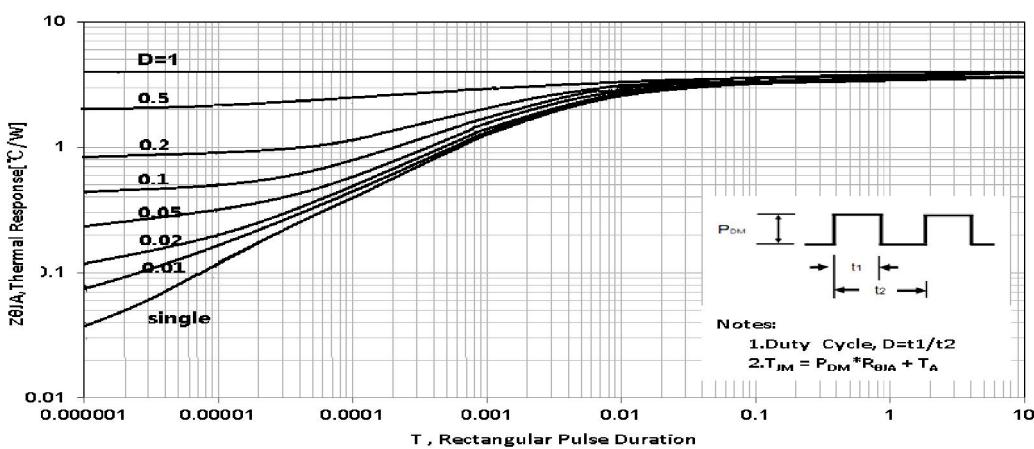
Source-Drain Diode Characteristics $T_J=25^\circ\text{C}$ unless otherwise specified

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
I_S	Continuous Source Current (Body Diode)	--	--	21	A	$T_C=25^\circ\text{C}$
I_{SM}	Maximum Pulsed Current (Body Diode)	--	--	84	A	
V_{SD}	Diode Forward Voltage	--	--	1.5	V	$I_{SD}=10\text{A}, V_{GS}=0\text{V}$
t_{rr}	Reverse Recovery Time	--	22.6	--	ns	$di/dt=100\text{A}/\mu\text{s}$ $I_S=10\text{A}$
Q_{rr}	Reverse Recovery Charge	--	16.7	--	nC	
Pulse width $\leq 300\mu\text{s}$; duty cycle $\leq 2\%$						

Notes:

*1. Repetitive rating; pulse width limited by maximum junction temperature.

*2. $L=0.5\text{mH}$, $I_{AS}=13\text{A}$, Start $T_J=25^\circ\text{C}$

Characteristics Curve:

Figure 1. Maximum Safe Operating Area

Figure 2. Maximum Power Dissipation vs Case Temperature

Figure 3. Maximum Continuous Drain Current vs Case Temperature

Figure 4. Typical output Characteristics

Figure 5 Maximum Effective Thermal Impedance , Junction to Case

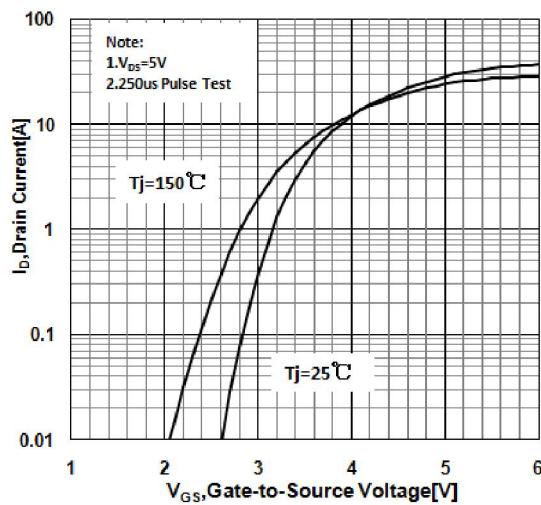


Figure 6 Typical Transfer Characteristics

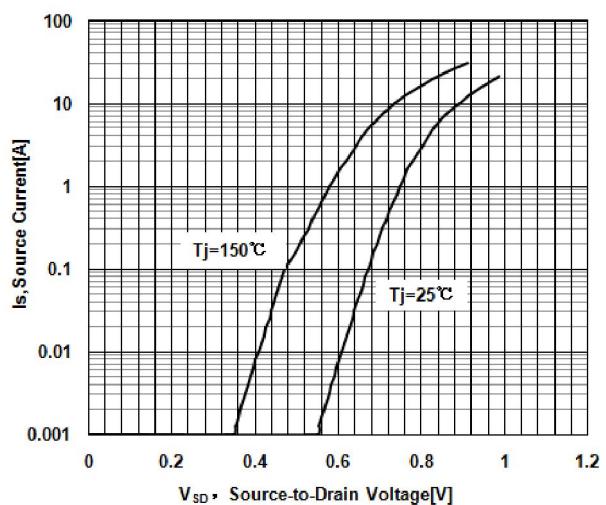


Figure 7 Typical Body Diode Transfer Characteristics

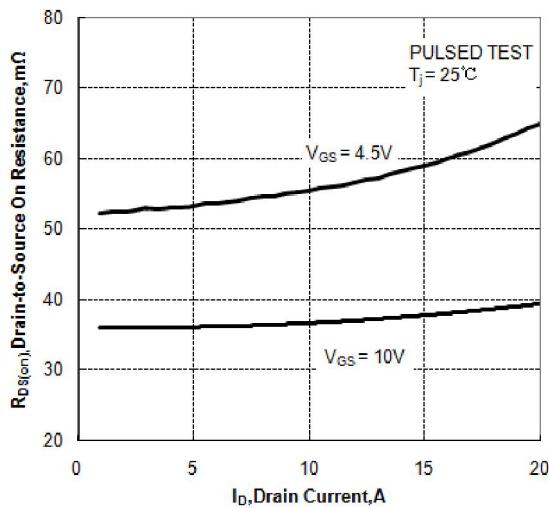


Figure 8. Drain-to-Source On Resistance vs Drain Current

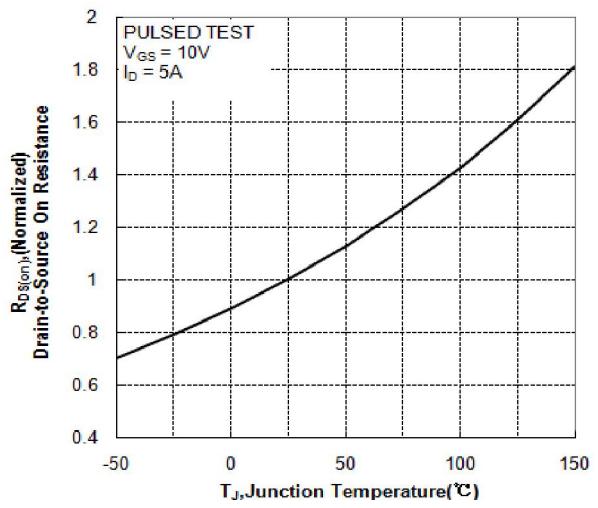


Figure 9. Normalized On Resistance vs Junction Temperature

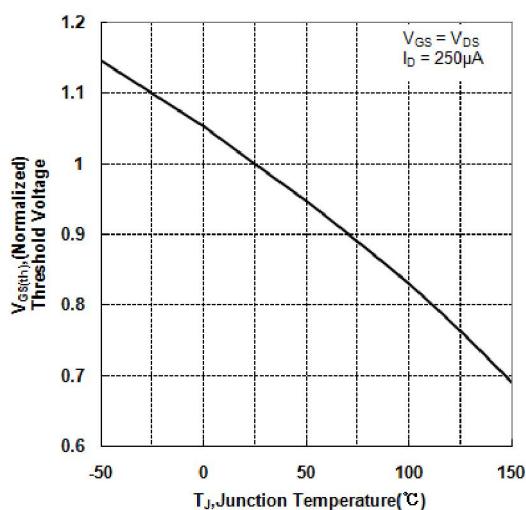


Figure10. Normalized Threshold Voltage vs Junction Temperature

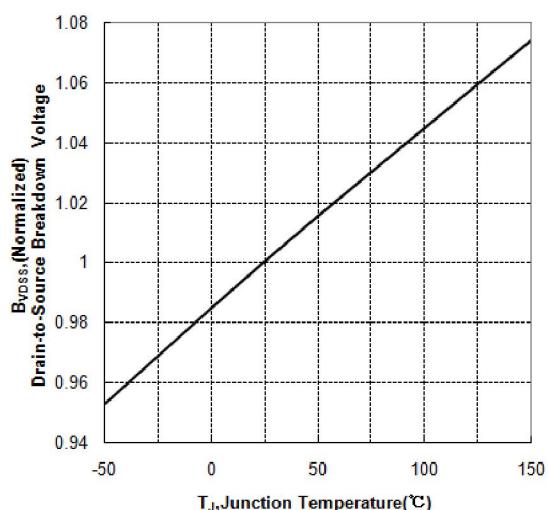
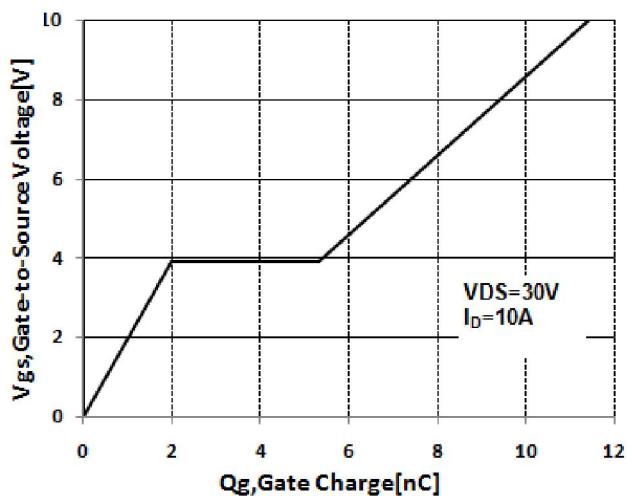
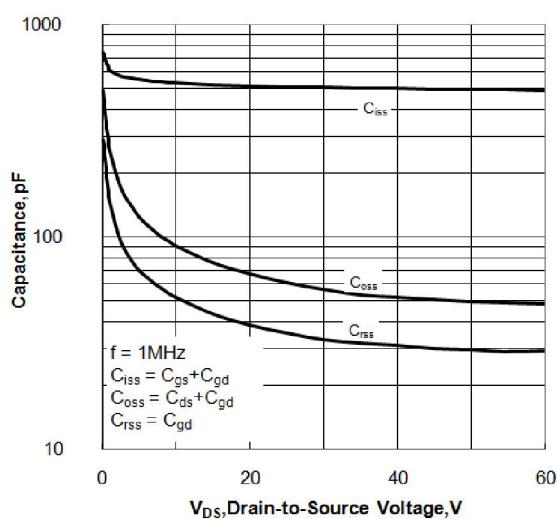


Figure 11. Normalized Breakdown Voltage vs Junction Temperature



Test Circuits and Waveforms

Figure 14. Gate Charge Test Circuit

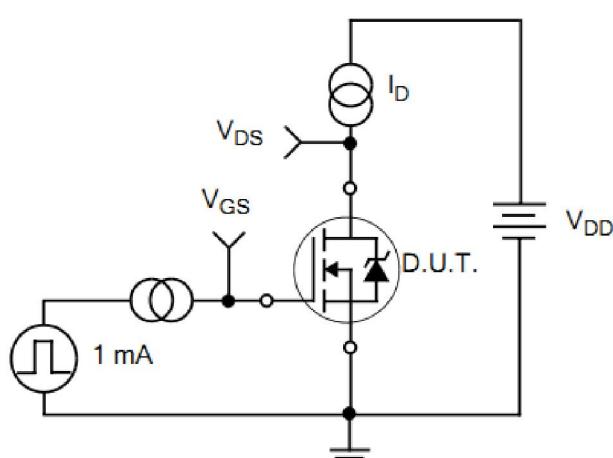


Figure 15. Gate Charge Waveforms

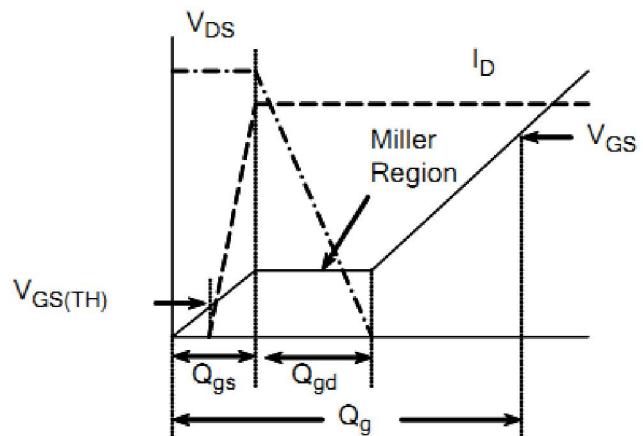


Figure 16. Resistive Switching Test Circuit

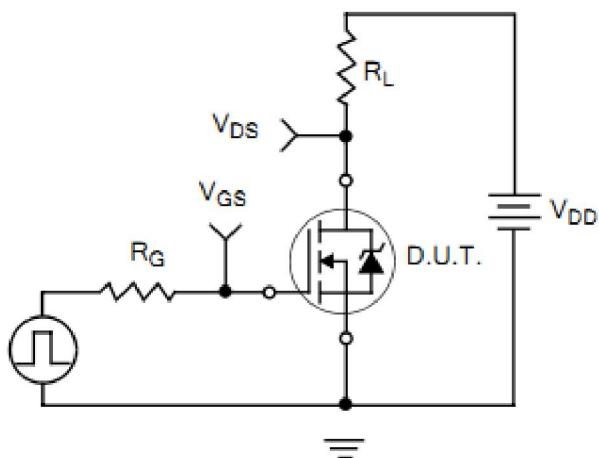


Figure 17. Resistive Switching Waveforms

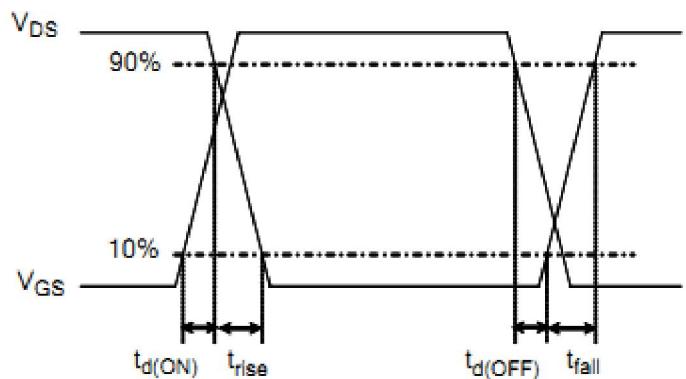


Figure 18. Diode Reverse Recovery Test Circuit

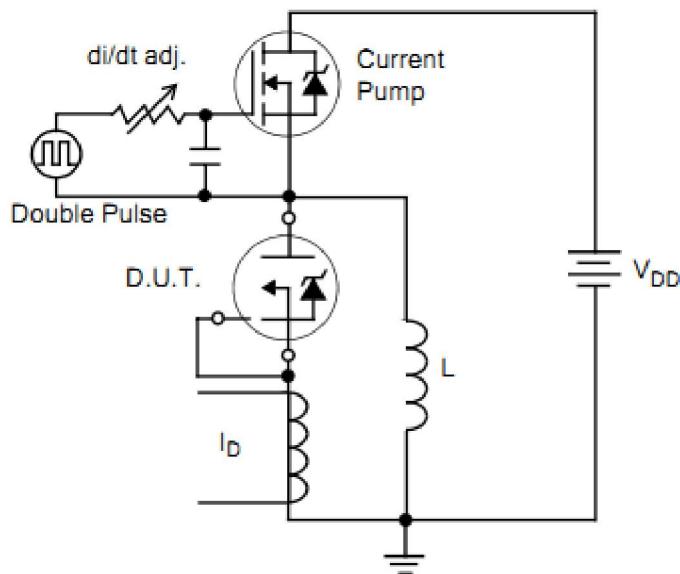


Figure 19. Diode Reverse Recovery Waveform

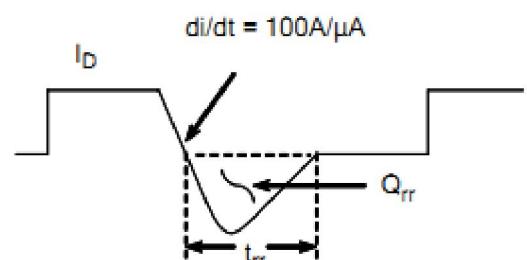


Figure20.Unclamped Inductive Switching Test Circuit

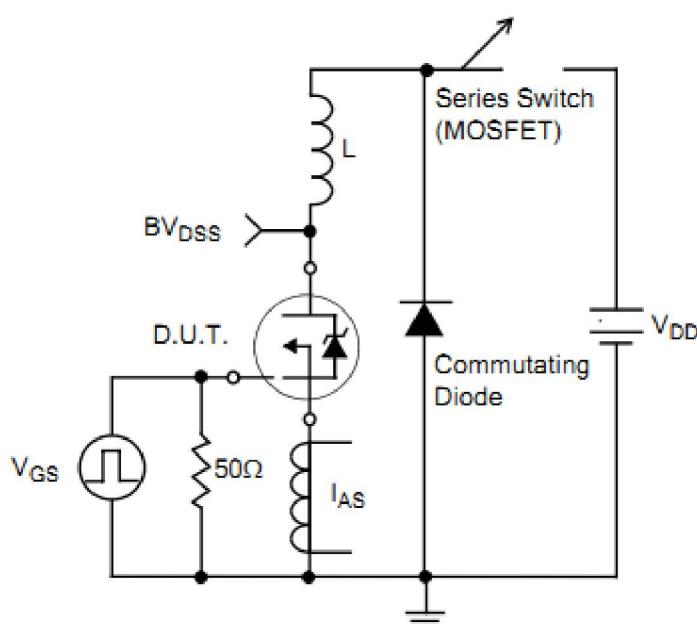
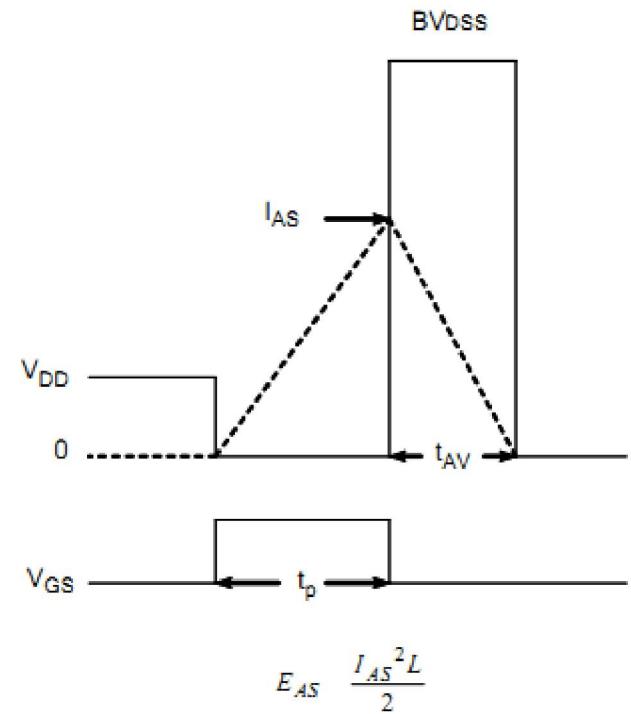


Figure21.Unclamped Inductive Switching Waveform



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